Powering ARM MCUs

Case Study:

STM32F4XX



STM32F4XX Overview

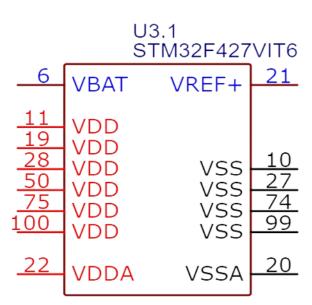
- Core: Arm® <u>32</u>-bit Cortex®-M4 CPU with FPU Adaptive real-time Accelerator (ART Accelerator[™]).
- Up to <u>2</u>MB Flash/<u>256+4</u>KB RAM.
- Operates from <u>1.8</u> V to <u>3.6</u> V, with minimum <u>1.7</u> V in reduced conditions.
- USB OTG HS/FS, Ethernet.
- <u>17</u> TIMs, <u>3</u> ADCs, <u>20</u> com. interfaces, camera & LCD-TFT.





Power Domains & Pins

- VBAT: RTC / backup registers
- VDD: Digital core & I/O
- VDDA: Analog supply for ADC, DAC
- VCAP1/2: Internal regulator caps (2.2 μF each)
- VREF+/-: External reference (in larger packages)

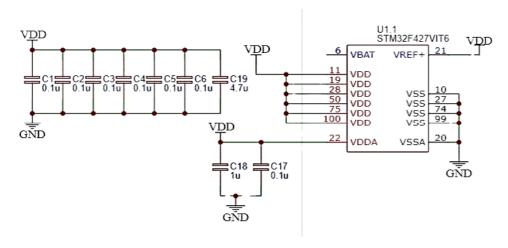


Supply Voltage Requirements

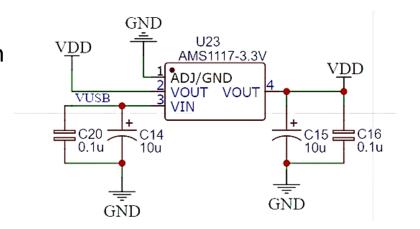
- VDD = $\underline{1.7}$ to $\underline{3.6}$ V: external power supply for I/Os and the internal regulator (when enabled), provided externally through VDD pins.
- VSSA, VDDA = <u>1.7</u> to <u>3.6</u> V: external analog power supplies for ADC, DAC, reset blocks, RCs, and PLL. VDDA and VSSA must be connected to VDD and VSS, respectively.
- VBAT = <u>1.65</u> to <u>3.6</u> V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when VDD is not present.

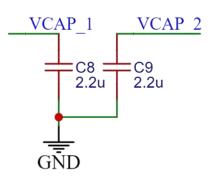
Power-Supply Circuit Essentials

■ Clean 3.3 V regulator required if powering via 5V(e.g.,USB) with [2*100nF] and [2*10µF] for filtering

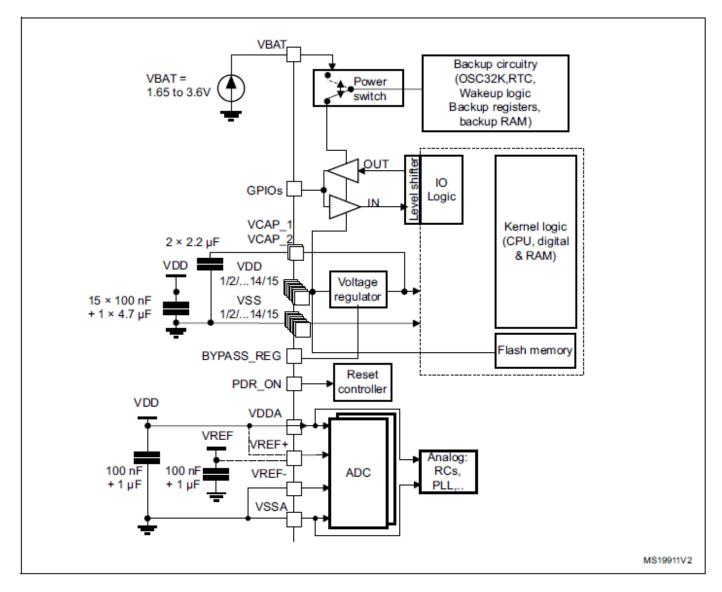


- Recommended decoupling :
 - □ VDD: $4.7 \mu F + 100 nF per pin$
 - \square VDDA: $\underline{1} \mu F + \underline{100} nF$; optional ferrite bead to VDD
 - \square VREF+: $\underline{1} \mu F + \underline{100} nF$ if used
 - □ VCAP1/VCAP2: 2.2 µF ceramic, low ESR





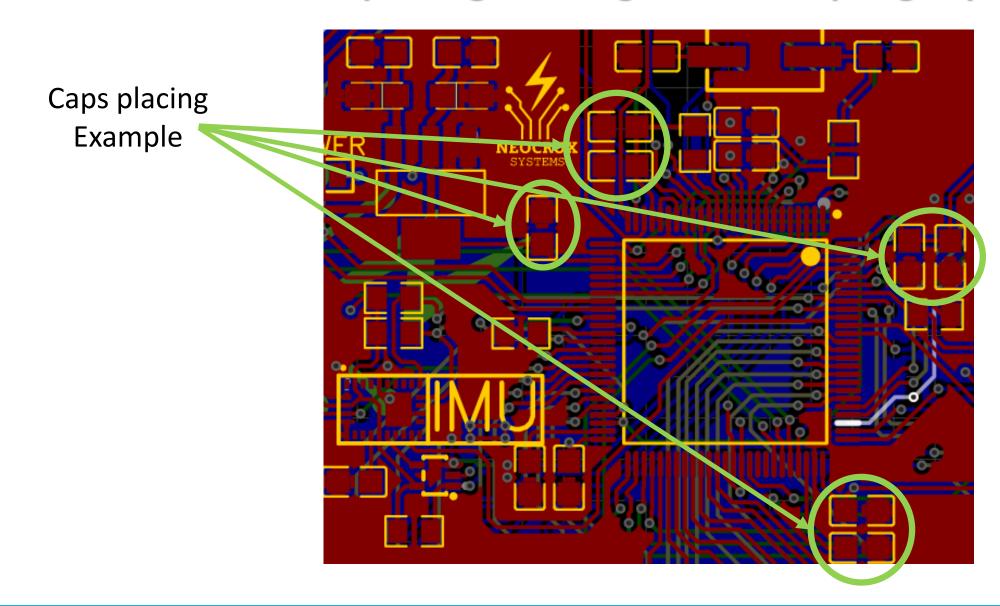
Power-Supply Circuit Essentials



Layout recommendations for placing filtering and decoupling capacitors

- Place caps as close to each VDD/VSSA/VREF pin as possible.
- Optimize via placement:
 - For each cap, route short, wide traces to separate power and ground vias.
 - Keep these vias close-directly adjacent to the capacitor pads.
 - Avoid long via-to-pad-to-via loops.
- Use both high-frequency and bulk capacitors:
 - Place 0.1 μF MLCC caps right at each power pin for high-frequency noise.
 - Add bulk <u>4.7</u>–<u>10</u> μF caps nearby for low-frequency stabilization.

Layout recommendations for placing filtering and decoupling capacitors



Low-Power Design Techniques

- Clock scaling: Reduce frequency during idle
- Voltage scaling: Lower core voltage saves leakage power
- Use sleep/deep-sleep: Leverage Stop/Standby modes
- Disable unused peripherals & GPIOs
- Power gating: Only power necessary blocks

- STM32-Specific Optimization (AN4635):
 - Best low-power achieved using MSI at 4 MHz, LPRUN regulator
 - Typical Stop mode current: $\approx 44 \mu A$
 - Lower clock & AHB divider improve efficiency